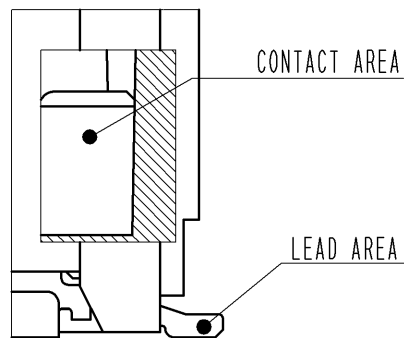
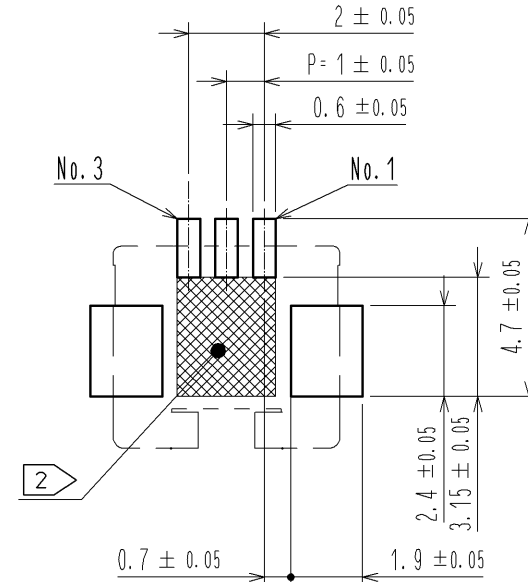


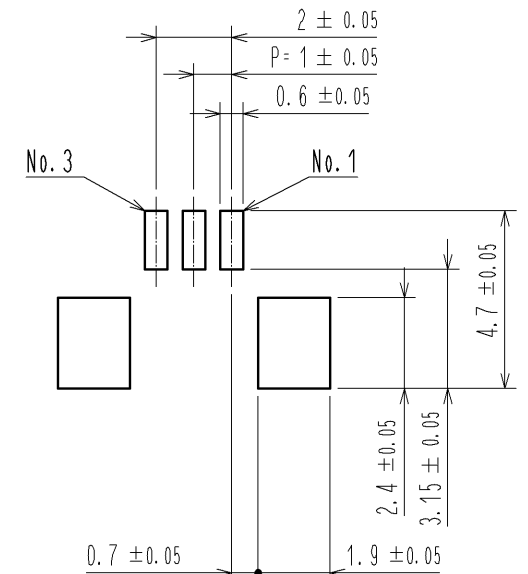
A (10:1)



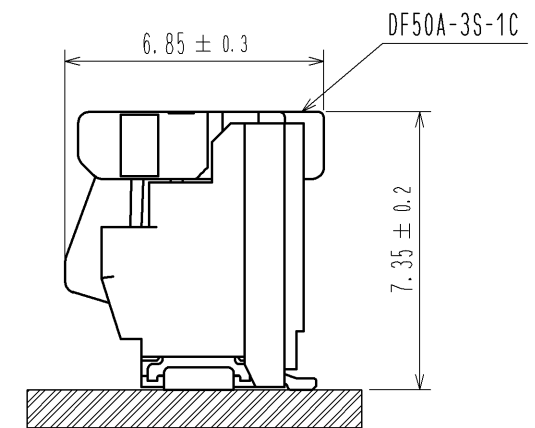
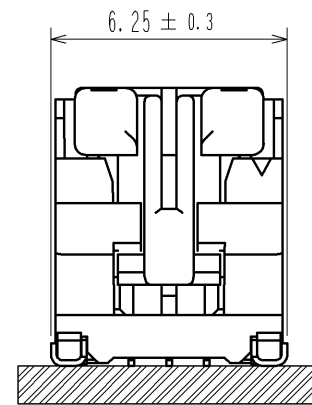
RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE) (FREE)



RECOMMENDED METAL MASK (FREE)  
THICKNESS : 0.1mm  
OPEN AREA RATIO:100%



MATING FIGURE(5:1)



- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX  
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.  
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	PHOSPHOR BRONZE	CONTACT AREA : Sn PLATING 1μm MIN UNDER PLATING : Cu PLATING 0.3μm MIN			
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	6	PS	REEL . BLACK
1	LCP	BLACK . UL94V-0	5	POLYESTER	CLEAR
			4	PS	CLEAR
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 5 : 1	COUNT △	DESCRIPTION OF REVISIONS	
DESIGNED		CHECKED		DATE	
APPROVED : KI. AKIYAMA		12.06.19		DRAWING NO. EDC3-329220-01	
CHECED : HK. UMEHARA		12.06.19		PART NO. DF50A-3P-1V(51)	
DESIGNED : ST. SATO		12.06.19		CODE NO. CL665-1004-1-51	
DRAWN : ST. SATO		12.06.19		△ 1/2	

